PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7206435

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DANIEL PAZ	12/28/2021
AMIT BAR-OR TILLINGER	12/26/2021
MICHAEL LEVITSKY	01/28/2022
ASSAF TOUBOUL	02/14/2022
SHAY LANDIS	01/31/2022
RONEN SHAKED	12/27/2021

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED	
Street Address:	5775 MOREHOUSE DRIVE	
City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17644631

CORRESPONDENCE DATA

Fax Number: (619)235-0398

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 619-238-1900

Email: docketing@procopio.com,rebecca.golden@procopio.com PROCOPIO CORY HARGREAVES & SAVITCH LLP **Correspondent Name:**

525 B STREET, SUITE 2200 Address Line 1:

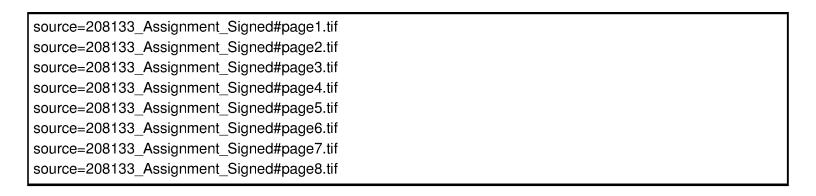
Address Line 4: SAN DIEGO, CALIFORNIA 92101

ATTORNEY DOCKET NUMBER:	129025-1191UT01/208133	
NAME OF SUBMITTER:	REBECCA GOLDEN	
SIGNATURE:	/REBECCA GOLDEN/	
DATE SIGNED:	03/03/2022	
·		

Total Attachments: 8

PATENT REEL: 059164 FRAME: 0613

507159590



ASSIGNMENT

WHEREAS, WE,

- 1. Daniel PAZ, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S. A.,
- 2. Amit BAR-OR TILLINGER, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,
- 3. Michael LEVITSKY, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,
- 4. Assaf TOUBOUL, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,
- 5. Shay LANDIS, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U. S.A.,
- 6. Ronen SHAKED, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to MULTI-LEVEL CODING FOR POWER EFFICIENT CHANNEL CODING (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to **U.S. Application No(s).** 17/644,631 filed **December 16, 2021**, **Qualcomm Reference Number 208133**, and all provisional applications relating thereto (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number (s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its

Qualcomm Reference Number: 208133

Page 2 of 8

v1

assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States or in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument:

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

Document ID: 1640193704836 v1

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Geva Carmel, Israel on All/12/24

City, State, Country Date Daniel PAZ

Qualcomm Reference Number: 208133 Document ID: 1640193704837 v1

Page 4 of 8

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at

Tel-Aviv, Israel

~12/26/21

City, State, Country

Same.

Amii BAR OR TILLINGER

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at

Rehovot, Israel

03

City, State, Country

Date

Michael LEVITSKY

Qualcomm Reference Number: 208133 Document ID: 1640193704839 v1

Page 6 of 8

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Netanya, Israel Done at

City, State, Country

Qualcomm Reference Number: 208133

Page 7 of 8

Document ID: 1640193704840 v1

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Hod Hasharon, Israel
Done at

on 31/1/2022

City, State, Country

Date

Shay LANDIS

Qualcomm Reference Number: 208133 Document ID: 1640193704841 v1

Page 8 of 8

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at

Kfar Saba, Israel

on 12-27-202

City, State, Country

Date

Ronen SHAKED

PATENT REEL: 059164 FRAME: 0622

RECORDED: 03/03/2022